



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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- ZENER DIODES
- LEADLESS PACKAGE FOR SURFACE MOUNT
- DOUBLE PLUG CONSTRUCTION
- METALLURGICALLY BONDED

**BZV55 C2V4
thru
BZV55 C75**

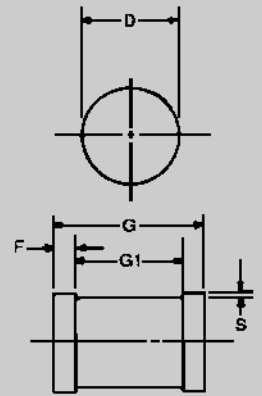
MAXIMUM RATINGS

Operating Temperature: -65°C to +175°C
 Storage Temperature: -65°C to +175°C
 Power Derating: 3.33 mW / °C above +50°C
 Forward Voltage: @ 200mA: 1.1 Volts maximum

ELECTRICAL CHARACTERISTICS @ 25°C, unless otherwise specified.

TYPE	ZENER VOLTAGE (NOTE 1) V _Z @ I _{ZT}			MAXIMUM DIFFERENTIAL RESISTANCE r _{diff} @ I _Z		MAXIMUM REVERSE CURRENT I _R @ V _R	
	VOLTS MIN	VOLTS MAX	mA	OHMS	mA	μA	VOLTS
BZV55 C2V4	2.2	2.6	5	100	5	50	1
BZV55 C2V7	2.5	2.9	5	100	5	20	1
BZV55 C3V0	2.8	3.2	5	95	5	10	1
BZV55 C3V3	3.1	3.5	5	95	5	5	1
BZV55 C3V6	3.4	3.8	5	90	5	5	1
BZV55 C3V9	3.7	4.1	5	90	5	3	1
BZV55 C4V3	4.0	4.6	5	90	5	3	1
BZV55 C4V7	4.4	5.0	5	80	5	3	2
BZV55 C5V1	4.8	5.4	5	60	5	2	2
BZV55 C5V6	5.2	6.0	5	40	5	1	2
BZV55 C6V2	5.8	6.6	5	10	5	3	4
BZV55 C6V8	6.4	7.2	5	15	5	2	4
BZV55 C7V5	7.0	7.9	5	15	5	1	5
BZV55 C8V2	7.7	8.7	5	15	5	.700	5
BZV55 C9V1	8.5	9.6	5	15	5	.500	6
BZV55 C10	9.4	10.6	5	20	5	.200	7
BZV55 C11	10.4	11.6	5	20	5	.100	8
BZV55 C12	11.4	12.7	5	25	5	.100	8
BZV55 C13	12.4	14.1	5	30	5	.100	8
BZV55 C15	13.8	15.6	5	30	5	.050	10.5
BZV55 C16	15.3	17.1	5	40	5	.050	11.2
BZV55 C18	16.8	19.1	5	45	5	.050	12.6
BZV55 C20	18.8	21.2	5	55	5	.050	14.0
BZV55 C22	20.8	23.3	5	55	5	.050	15.4
BZV55 C24	22.8	25.6	5	70	5	.050	16.8
BZV55 C27	25.1	28.9	2	80	2	.050	18.9
BZV55 C30	28.0	32.0	2	80	2	.050	21.0
BZV55 C33	31.0	35.0	2	80	2	.050	23.1
BZV55 C36	34.0	38.0	2	90	2	.050	25.2
BZV55 C39	37.0	41.0	2	130	2	.050	27.3
BZV55 C43	40.0	46.0	2	150	2	.050	30.1
BZV55 C47	44.0	50.0	2	170	2	.050	32.9
BZV55 C51	48.0	54.0	2	180	2	.050	35.7
BZV55 C56	52.0	60.0	2	200	2	.050	39.2
BZV55 C62	58.0	66.0	2	215	2	.050	43.4
BZV55 C68	64.0	72.0	2	240	2	.050	47.6
BZV55 C75	70.0	79.0	2	255	2	.050	52.2

NOTE 1 Nominal Zener voltage is measured with the device junction in thermal equilibrium at an ambient temperature of 25°C ± 3°C.



	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
D	1.60	1.70	0.063	0.067
F	0.41	0.55	0.016	0.022
G	3.30	3.70	.130	.146
G1	2.54 REF.		.100 REF.	
S	0.03 MIN.		.001 MIN.	

DESIGN DATA

CASE: DO-213AA, Hermetically sealed glass case. (MELF, SOD-80, LL34)

LEAD FINISH: Tin / Lead

THERMAL RESISTANCE: (R_{QJEC}): 100 °C/W maximum at L = 0 inch

THERMAL IMPEDANCE: (Z_{QJX}): 35 °C/W maximum

POLARITY: Diode to be operated with the banded (cathode) end positive.

MOUNTING SURFACE SELECTION: The Axial Coefficient of Expansion (COE) Of this Device is Approximately +6PPM/°C. The COE of the Mounting Surface System Should Be Selected To Provide A Suitable Match With This Device.

